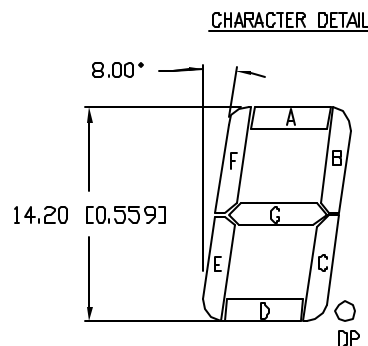
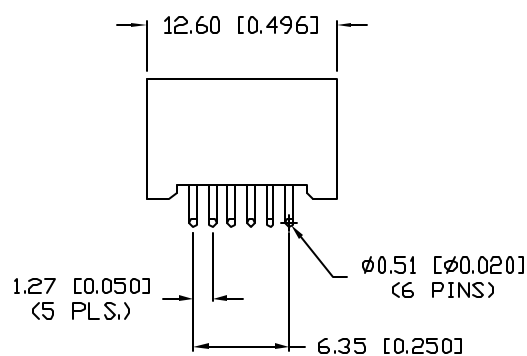
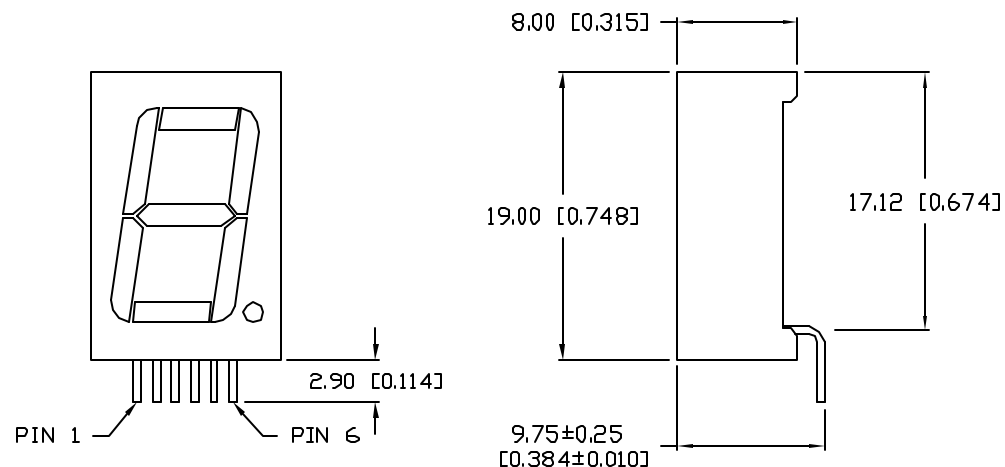


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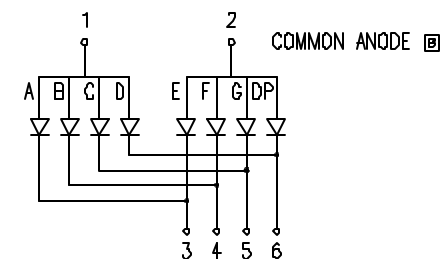
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN.	7-13-99
B	E.C.N. #10574.	12-20-99

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=10\text{mA}$					
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585 (YELLOW)		nm	
FORWARD VOLTAGE		2.1	2.5	V _f	
REVERSE VOLTAGE	5.0			V _r	I _r =100μA
AXIAL INTENSITY		2250		μcd	I _f =10mA
EMITTED COLOR:	YELLOW				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY	3 SEC. MAX	

* $t < 10\mu\text{s}$



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*UNLESS OTHERWISE SPECIFIED TOLERANCE IS $\pm 0.25\text{mm}$ ($\pm 0.010"$)

REV.
B

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RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

LUMEX
INCORPORATED

290 E. HELLEN ROAD
PALATINE, ILLINOIS 60067
PHONE: 1-847-359-2790
WEB: HTTP://WWW.LUMEX.COM

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 11-13-95
			PAGE: 1 OF 1
			SCALE: N/A

0.56" SEVEN SEGMENT SINGLE DIGIT DISPLAY,
585nm YELLOW CHIPS, GRAY FACE WITH WHITE SEGMENTS,
COMMON ANODE, RIGHT DECIMAL POINT.

TM/BC